



Package Bill of Material Gold (Au) To Copper (Cu) Wire Change for Spartan-3, Spartan-3E and Spartan-3A FPGA Products

XCN11002 (v1.0) August 15, 2011

Product Change Notice

Overview

The purpose of this notification is to announce the transitioning of all wire bond package types for Spartan®-3, Spartan-3E and Spartan-3A FPGA products from gold (Au) to copper (Cu) wire. For the Cu-wire assembly, only halogen free, EU-ROHS compliant packages and green mold compound will be used. These packages do not contain published REACH SvHC materials.

Description

Xilinx's conversion to copper wire is to align with the current industry trend to better support long-term demand for the affected products. Copper wire has demonstrated better electrical and mechanical performance than gold wire. Xilinx assembly suppliers have qualified copper wire technology and have been using it in high volume production since 2008. Any planned capacity expansion will be for copper wire packages only.

This change will not affect fit, form, function or MSL rating of the packages. For Cu-wire assembly, the packages are halogen free, EU-RoHS compliant with green mold compound, and do not contain published REACH SvHC materials. Xilinx will continue to support packages assembled with tin lead (SnPb) solder balls and leadframe plating.

Products Affected

This change affects all speed, package, and temperature variations of "XC" commercial (C) and industrial (I) grade product families mentioned in the title and overview. Automotive "XA" and Aerospace/Defense "XQ" are not affected.

Key Dates and Ordering Information

Xilinx will begin to cross-ship products using both gold wire and copper wire per the [Table 1](#) schedule.

Table 1: Spartan-3 FPGA Products Cross-Ship Schedule

Devices	Packages	Target Cross Shipping Date
Spartan-3/-3E/-3A	VQ(G)100 TQ(G)144 PQ(G)208	November, 2011
Spartan-3/-3E/-3A	CP(G)132 FT(G)256 FG(G)320 FG(G)400 FG(G)456 FG(G)484 FG(G)676 FG(G)900 FG(G)1156	January, 2012*

* Phase In Begins

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Qualification Data

Xilinx has successfully passed and completed the Cu wire qualification. Please refer to Xilinx [RPT156](#) for more detail.

Response

No response is required. For additional information or questions, please contact [Xilinx Technical Support](#).

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Additional Documentation

Qualification Report (RPT156):

<https://secure.xilinx.com/webreg/clickthrough.do?cid=173884>.

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
08/15/11	1.0	Initial release.

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